

REMARKS/ARGUMENTS

The specification has been amended at page 18, line 25, changing "Comparative Examples 1 to 15" to "Comparative Examples 1 to 11".

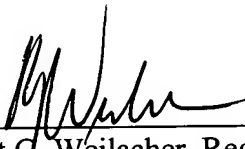
Table 2 of the specification has been amended to delete original Comparative Examples 2, 3, 7 and 9 and the examples are renumbered. A clean copy and marked up copy are enclosed.

New Claim 9 has been added based on the proportions of components C, E and F disclosed on page 4, lines 16-17, page 7, line 9; and page 14, line 22, respectively.

Examination on the merits is awaited.

Respectfully submitted,

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TABLE 2

		Comparative Example																
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19
Phenol biphenyl/alkyl type epoxy resin	7.4	3.6	9.5	9.4		7.4	7.5	7.4	7.6	7.35	7.35	7.4	7.35	7.35				
Biphenyl type epoxy resin		0.8																
Cresol novolac type epoxy resin					6.9													
Phenol biphenyl/alkyl resin	5.5	2.3	6.35			5.5	5.52	6.48	5.65	5.5	5.5	5.5	5.5	5.5	5.5	5.5	5.5	5.5
Phenol/alkyl resin		4.0			6.0													
Phenol novolac resin				3.5														
Spherical fused silica	86.0	84.0	83.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0
γ-Glycidylpropyltrimethoxysilane	0.4	0.5	0.3	0.4	0.4	0.4	0.4	0.4		0.4	0.4	0.4	0.4	0.4	0.4	0.4	0.4	0.4
7-Me rcapto pro pyltrimethoxysilane																		
Triphenylphosphine	0.2	0.43	0.25	0.15	0.15	0.2	0.06	0.2	0.2	0.2	0.2							
DBU												0.2						
Curing accelerator of formula C7)													0.25					
Curing accelerator of formula C8)																		0.25
2,3-Dihydroxynaphthalene		0.07	0.4	0.05	0.05	0.55		0.008	0.05									
1,2-Dihydroxynaphthalene																		
Catechol																		
Pyrogallol																		
1,6-Dihydroxynaphthalene										0.05								
Resorcinol											0.05							
Carnauba wax	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2
Carbon black	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3
Spiral flow (cm)	80	63	426	76	71	62	114	84	76	78	81	68	89	77				
Curing torque ratio (%)	65	62	66	67	70	62	7	66	56	65	64	57	85	89				
Solder resistance-cracking	4	chip	0	2	chip	3		4	9	5	4	4	2	3				
Chip delamination		exposure	2	10	exposure	0	Poor releasing	0	0	0	0	0	0	0				
Internal crack	0	V-O	V-1	V-1	HB	V-O		V-O	V-O	V-O	V-O	V-O	V-O	V-O	V-O	V-O	V-O	V-O
Fire retardancy	V-O	V-O	V-1	V-1	HB	V-O		V-O	V-O	V-O	V-O	V-O	V-O	V-O	V-O	V-O	V-O	V-O